

# **CX4SM AT CRYSTAL**

14 MHz to 250 MHz Ultra-Miniature, Low Profile

Ultra-Miniature, Low Profile Surface Mount AT Quartz Crystal

#### **DESCRIPTION**

STATEK's ultra-miniature CX4SM AT crystals in leadless ceramic packages are designed for surface mounting on printed circuit boards or hybrid substrates. These crystals are low profile and have a very small land pattern.

## **FEATURES**

- Designed for surface mount applications using infrared, vapor phase, wave solder or epoxy mount techniques.
- Low profile (less than 1.2 mm) hermetically sealed ceramic package
- Excellent aging characteristics
- Available with glass or ceramic lid
- High shock and vibration resistance
- Custom designs available
- Full military testing available
- Designed and manufactured in the USA

# **APPLICATIONS**

## Medical

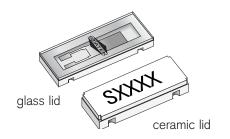
- Neurostimulators
- Cochlear Implants
- Implantable CRM
- Infusion Pumps
- Glucose Monitors

Industrial, Computer & Communications

- Instrumentation
- Process Control
- Environmental Control
- Engine Control
- Handheld Inventory Control
- Down-hole Data Recorder
- Telemetry

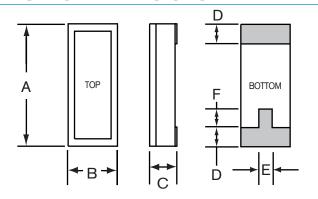
Military & Aerospace

- Communications Radio
- Smart Munitions
- Timing Devices (Fuzes)
- Surveillance Devices





### PACKAGE DIMENSIONS



	TYPICAL		MAX	MUM	
DIM	inches	mm	inches	mm	
А	0.197	5.00	0.210	5.33	
В	0.072	1.83	0.085	2.16	
С	-	-	see	below	
D	0.036	0.91	0.046	1.16	
Е	0.020	0.51	-	-	
F	0.025	0.64	-	-	

### THICKNESS (DIM C) MAXIMUM

	GLASS LID		CERAMIC LID		
	inches	mm	inches	mm	
SM1	0.045	1.14	0.050	1.27	
SM2/SM4	0.046	1.17	0.051	1.30	
SM3/SM5	0.048	1.22	0.053	1.35	

10150 - Rev. D



#### **SPECIFICATIONS**

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice.

14.7456 MHz	<u>16MHz</u>	<u>20 MHz</u>	<u>32 MHz</u>	<u>40 MHz</u>	<u>80 MHz</u>	<u>160 MHz</u>	<u>200 MHz</u>
) 60	75	50	30	30	30	30	40
1.4	1.5	1.4	2.5	1.5	1.8	2.5	2.0
120	90	110	70	90	40	20	15
0.8	0.9	0.9	1.1	1.0	1.0	1.5	1.5
	) 60 1.4 120	) 60 75 1.4 1.5 120 90	) 60 75 50 1.4 1.5 1.4 120 90 110	) 60 75 50 30 1.4 1.5 1.4 2.5 120 90 110 70	0 60 75 50 30 30   1.4 1.5 1.4 2.5 1.5   120 90 110 70 90	0 60 75 50 30 30 30   1.4 1.5 1.4 2.5 1.5 1.8   120 90 110 70 90 40	0 60 75 50 30 30 30 30   1.4 1.5 1.4 2.5 1.5 1.8 2.5   120 90 110 70 90 40 20

Calibration Tolerances¹  $\pm 100$  ppm, or tighter as required Load Capacitance  $\pm 10$  pF (unless specified otherwise) Drive Level  $\pm 200$   $\mu$ W MAX for f  $\pm 50$  MHz  $\pm 100$   $\mu$ W MAX for f  $\pm 50$  MHz

Frequency-Temperature ± 50 ppm to ± 10 ppm (Commercial) stability<sup>1,3</sup> ± 100 ppm to ± 20 ppm (Industrial)

± 100 ppm to ± 30 ppm (Military)

Aging, first year<sup>3</sup> 5 ppm MAX (better than 1 ppm available)

Shock, survival<sup>4</sup> 5,000 g, 0.3 ms, 1/2 sine

Vibration, survival<sup>5</sup> 20 g, 10-2,000 Hz swept sine

Operating Temp. Range -10°C to +70°C (Commercial)

-40°C to +85°C (Industrial) -55°C to +125°C (Military)

Storage Temp. Range -55°C to +125°C

Max Process Temperature 260°C for 20 sec.

- 1) Other tolerances available. Contact factory.
- Does not include calibration tolerance. The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.
- 5 ppm MAX for frequencies below 40 MHz. For tighter tolerances and higher frequencies contact factory.
- 4) Higher shock version available.
- 5) Per MIL-STD-202G, Method 204D, Condition D. Random vibration testing also available.

## PACKAGING OPTIONS

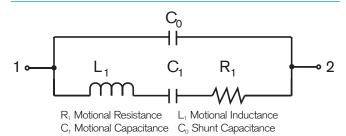
- Tray Pack
- Tape and Reel Per EIA 481 (see Tape and Reel data sheet 10109)

### **TERMINATIONS**

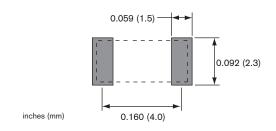
<u>Designation</u>	<u>Termination</u>
SM1	Gold Plated (Lead Free)
SM2	Solder Plated
SM3	Solder Dipped
SM4	Solder Plated (Lead Free)
SM5	Solder Dipped (Lead Free)

Max Process Temperature 260°C for 20 sec.

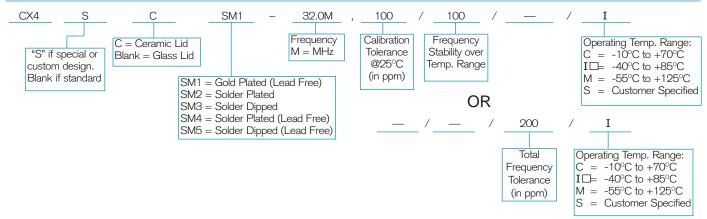
# **EQUIVALENT CIRCUIT**



### SUGGESTED LAND PATTERN



## HOW TO ORDER CX4SM AT CRYSTALS



10150 - Rev. D

